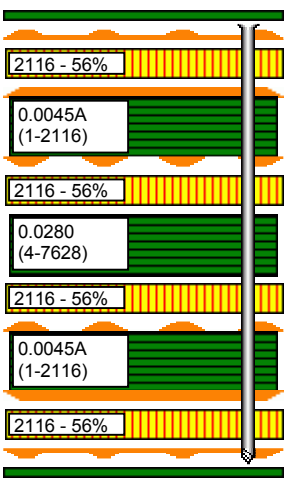




Layer	Cust Thickness	Calc Thickness	Primary Stack	Description	Dk / Df
Layer - 1		0.0005 0.0020		Taiyo 4000-MP 1/2oz Sig (Std Plt)	4.70 / 0.0330
Layer - 2		0.0046 0.0006		370H 1/2oz P/G	4.41 / 0.0210
Layer - 3		0.0045 0.0006 0.0042		370H 1/2oz Sig	4.43 / 0.0200
		0.0280		370H	4.51 / 0.0210
		0.0042 0.0006		370H 1/2oz Sig	4.51 / 0.0210
Layer - 4		0.0045		370H	4.43 / 0.0200
Layer - 5		0.0006 0.0046		1/2oz P/G 370H	4.41 / 0.0210
Layer - 6		0.0020 0.0005		1/2oz Sig (Std Plt) Taiyo 4000-MP	4.70 / 0.0330

Requirement	Req. Thickness	Tol +	Tol -	Calc Thick
Incl. Plating & Mask	0.0620	0.0062	0.0062	0.0620
Incl. Mask over Laminate	0.0580	0.0058	0.0058	0.0580
Incl. Plating	0.0610	0.0061	0.0061	0.0610
After Lamination	0.0582	0.0029	0.0029	0.0582
Over Laminate	0.0570	0.0057	0.0057	0.0570

Impedance Type	Layer	Design	Actual	Plotted	Pitch	Plane	Target	Tol (ohms)	Predict
 EC Stripline	L4	0.00394	0.0040	0.0045	0.0098	L2	100	10	99.92
	-	0.00394	0.0040	0.0045	-	L5			
 EC Microstrip	L6	0.00590	0.0061	0.00685	0.0216	L5	100	10	100.37
	-	0.00590	0.0061	0.00685	-	-			

#### Bill Of Materials

Material	Material Description	Qty per Panel
370H 0.0045A (1-2116) H H	Isola370HR High-Tg FR4	2
370H 0.0280 (4-7628) 0 0	Isola370HR High-Tg FR4	1
HTE6P	Copper Foil HTESHINY6%	2
370H 2116	Isola370HR High-Tg FR4	4